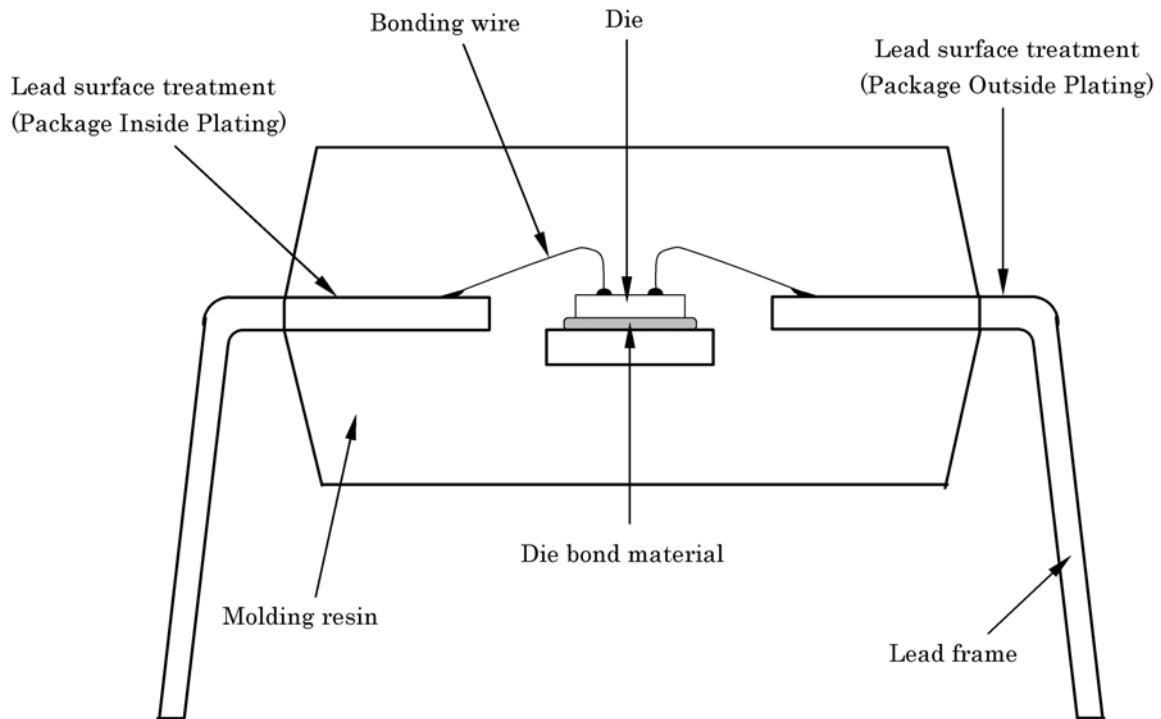


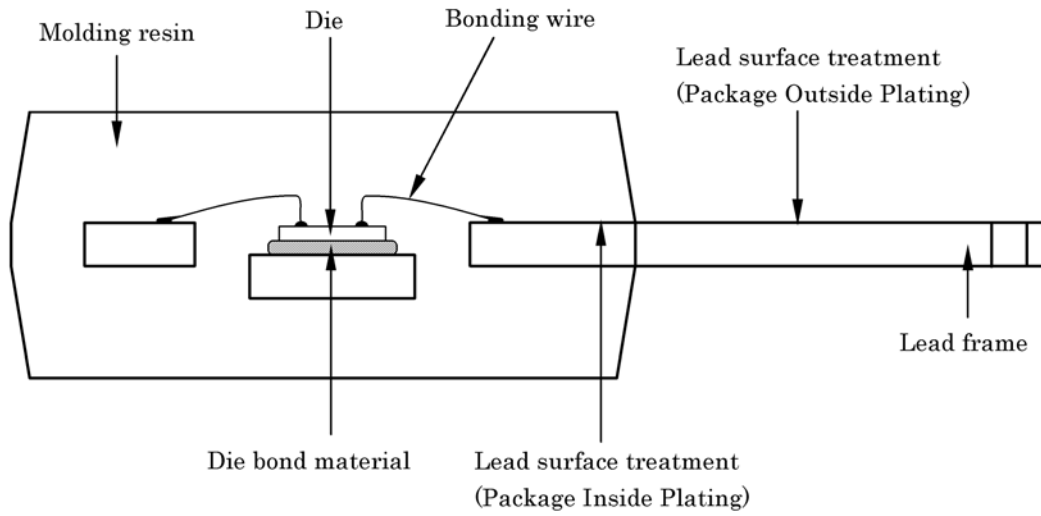
DIP/SDIP



- | | |
|------------------------------|-------------------------------|
| Die Attach | : Resin bonding method |
| Wire bonding method | : Thermal-Sonic Bonding (TSB) |
| Mold method | : Transfer mold |
| Flame class of molding resin | : UL94V-0 |

INNER STRUCTURE

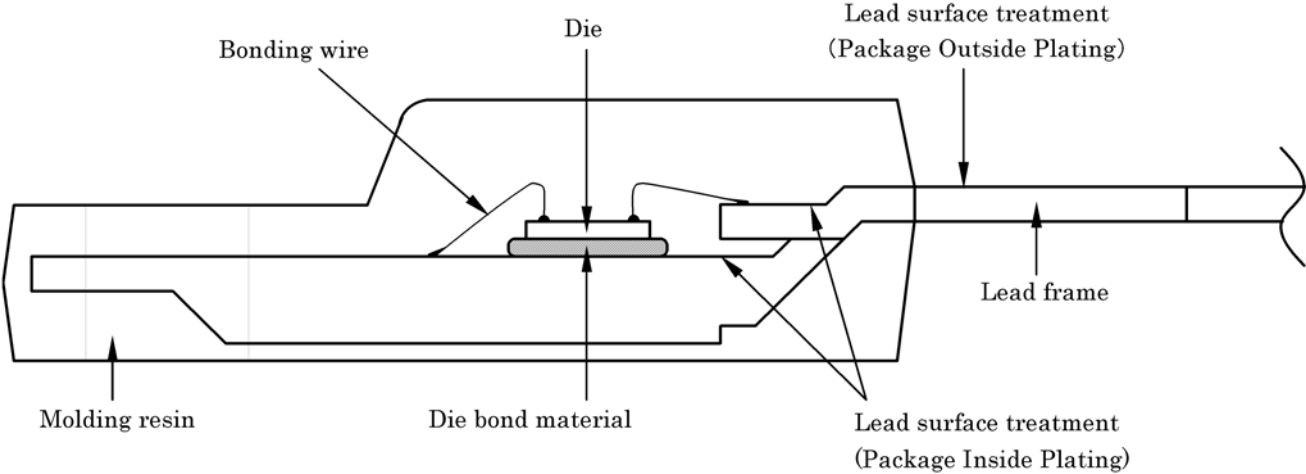
SIP



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

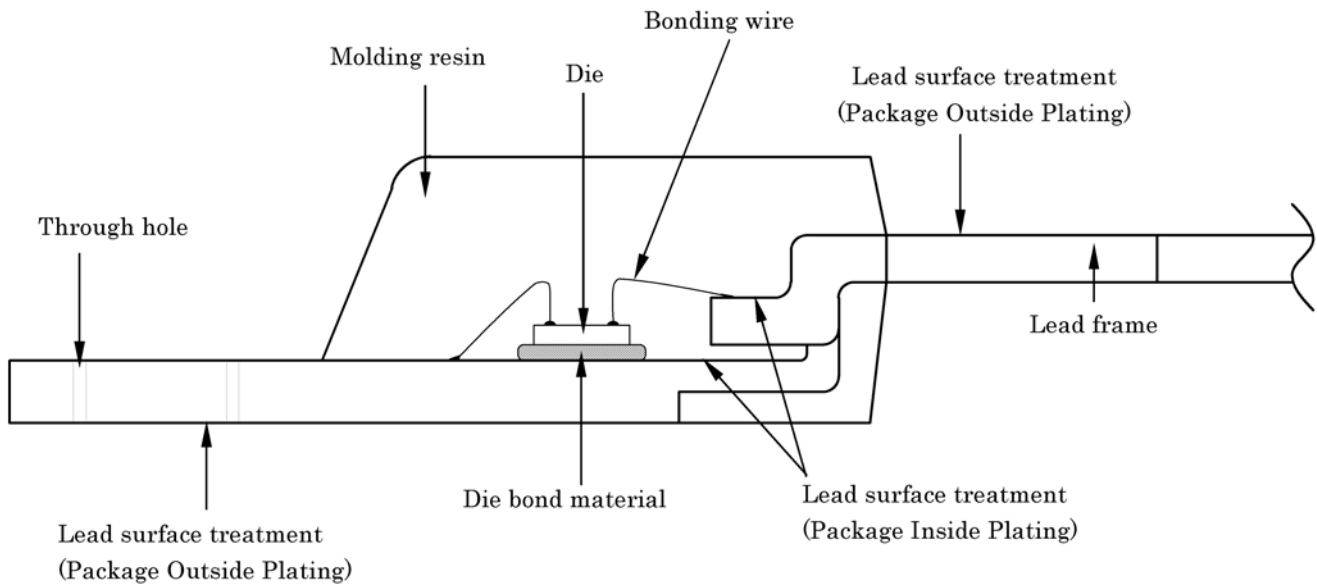
TO-220F



- Die Attach : Resin bonding method
- Wire bonding method : Thermal-Sonic Bonding (TSB)
- Mold method : Transfer mold
- Flame class : UL94V-0

INNER STRUCTURE

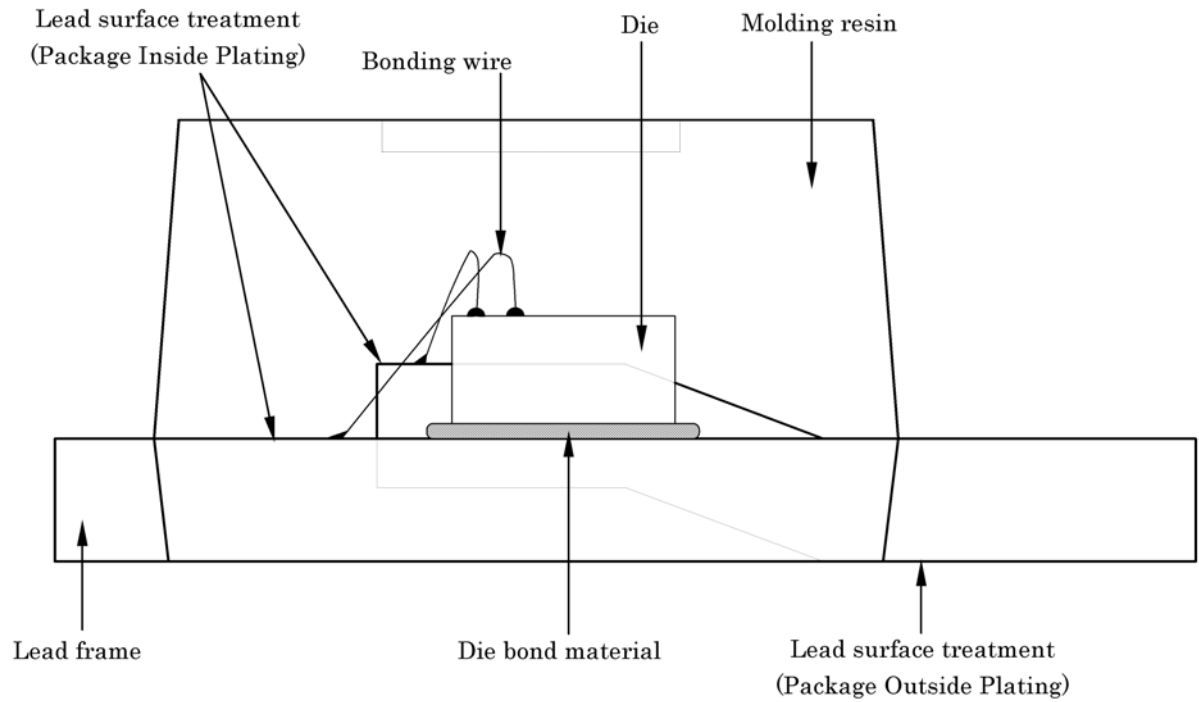
TO-220-5-A2/TO-220-5-LA2



Die Attach : Resin bonding method
Wire bonding method : Thermal-Sonic Bonding (TSB)
Mold method : Transfer mold
Flame class : UL94V-0

INNER STRUCTURE

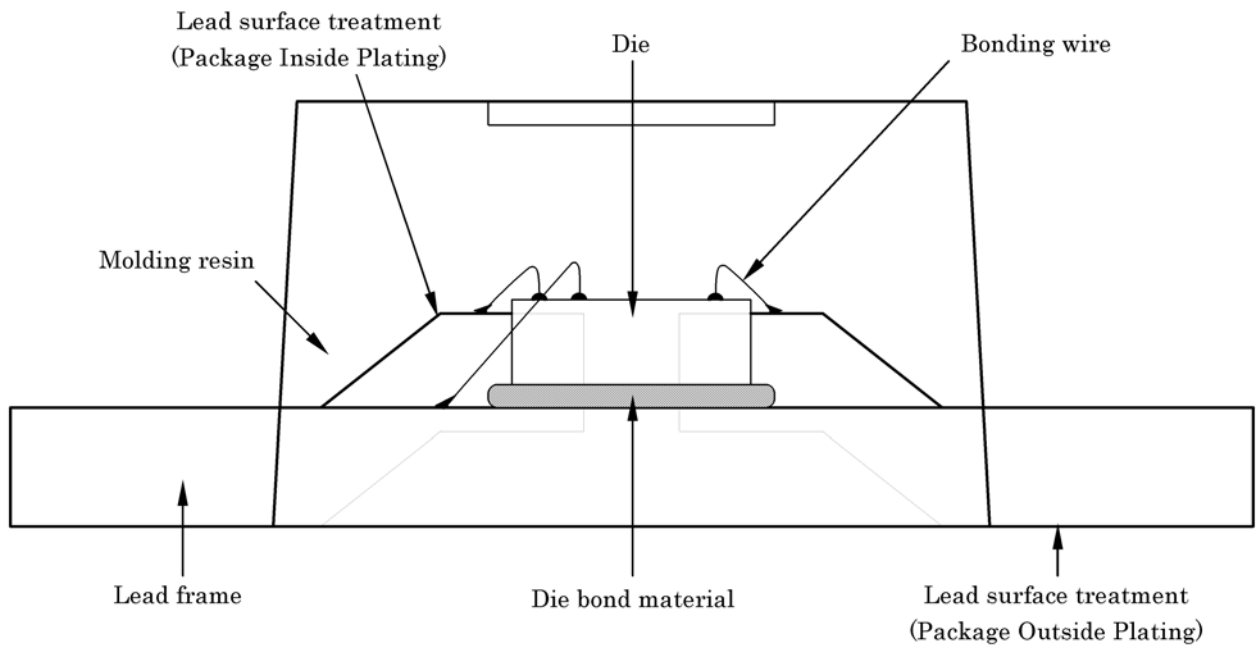
SOT-89-3



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

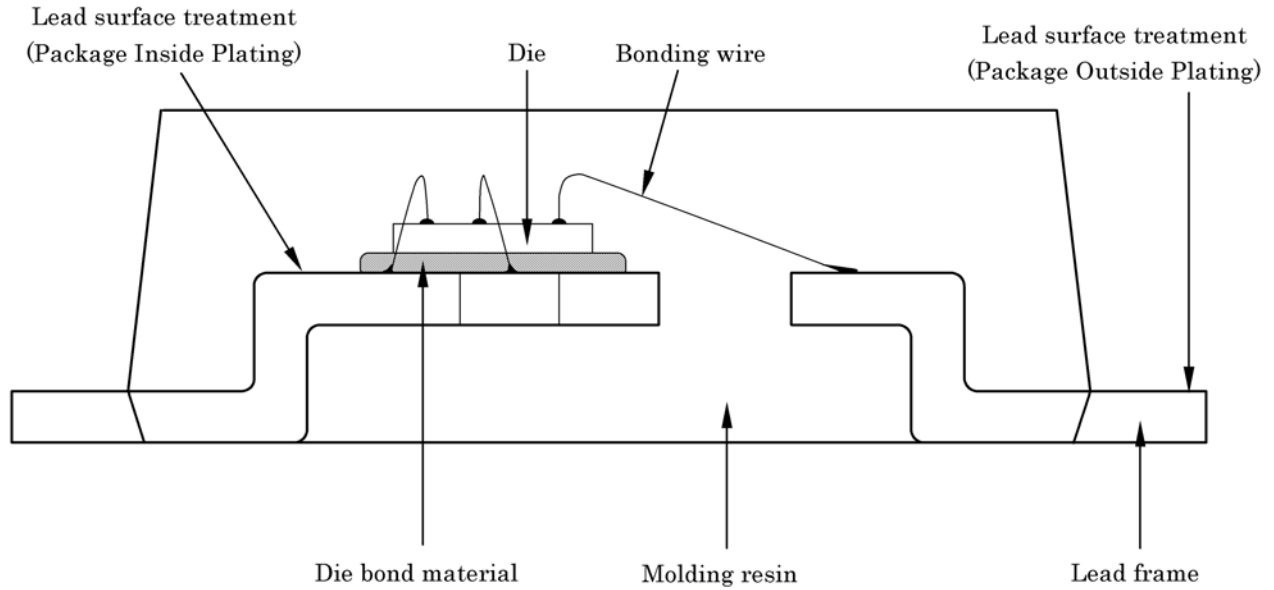
SOT-89-5



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

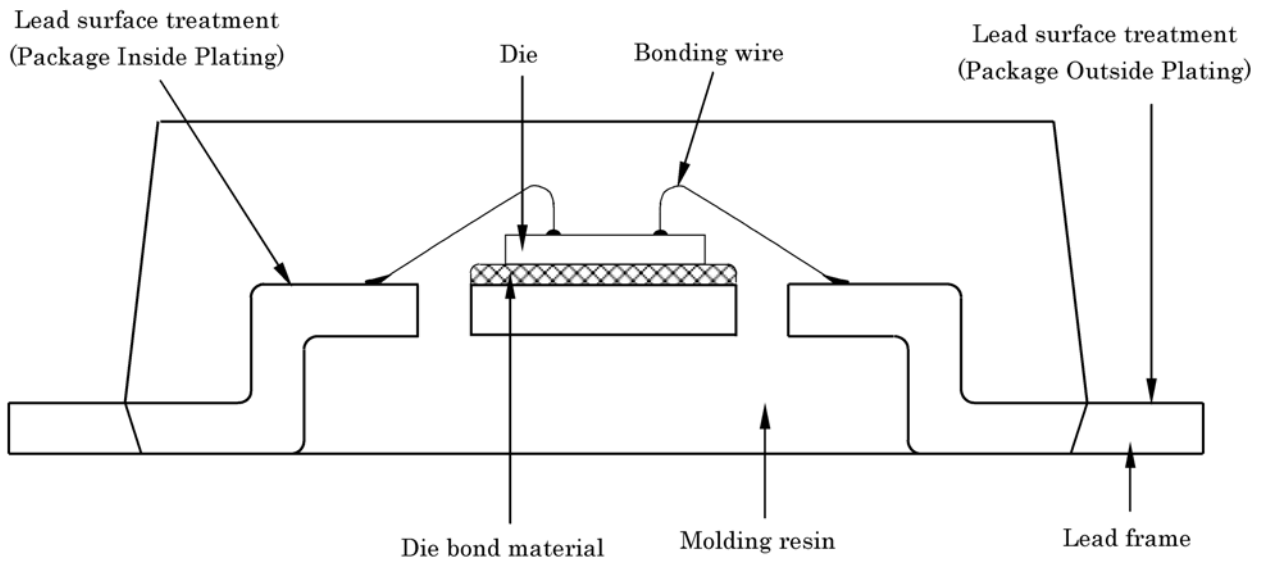
FLP6-B2/FLP10-C1



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

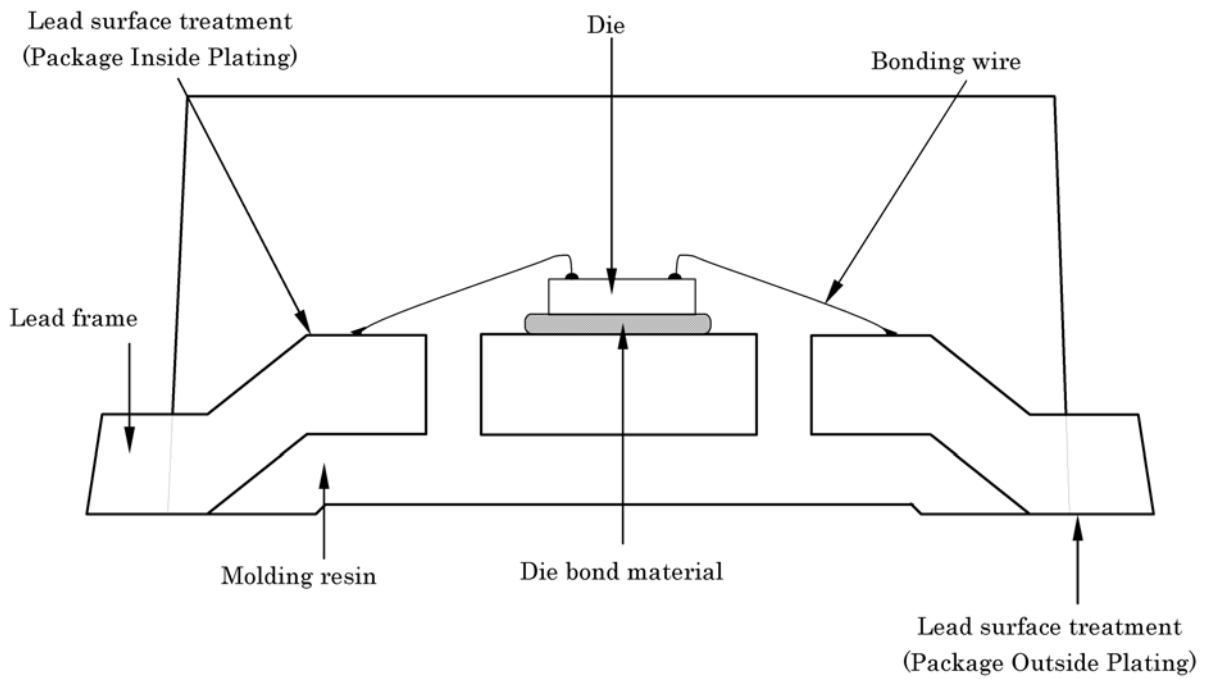
FLP6-A1



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

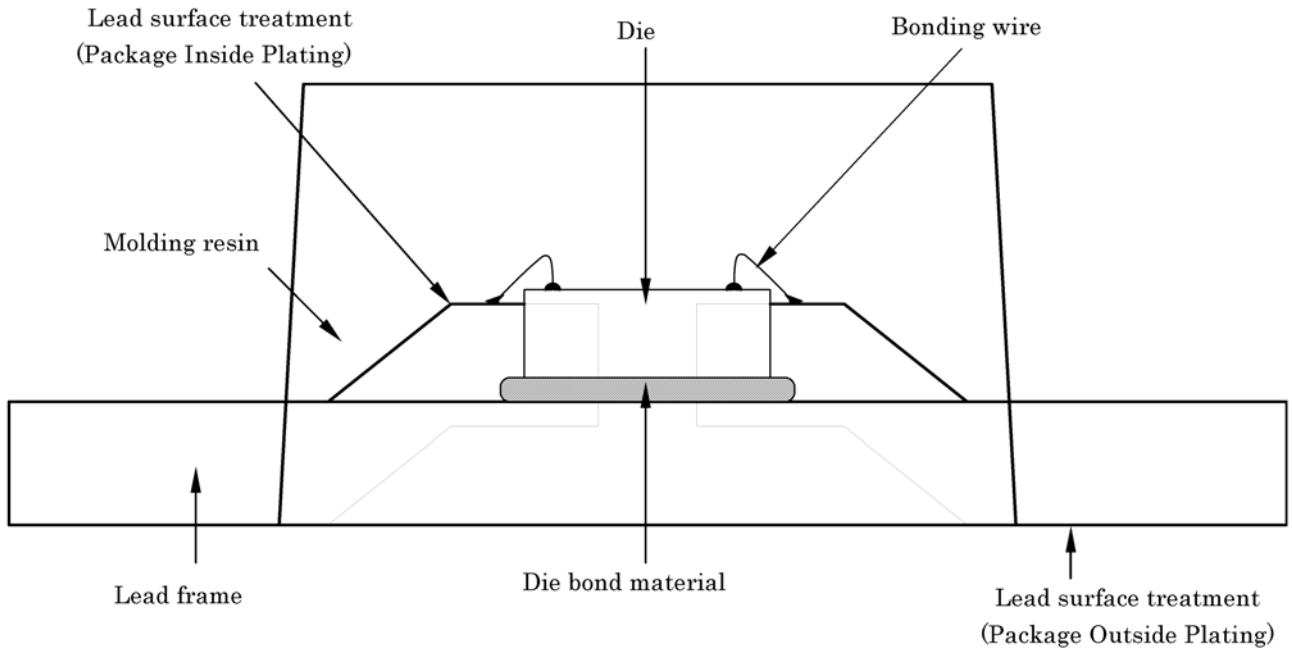
DFN6-J1(SON6-J1)/DFN10-K1(SON10-K1)



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

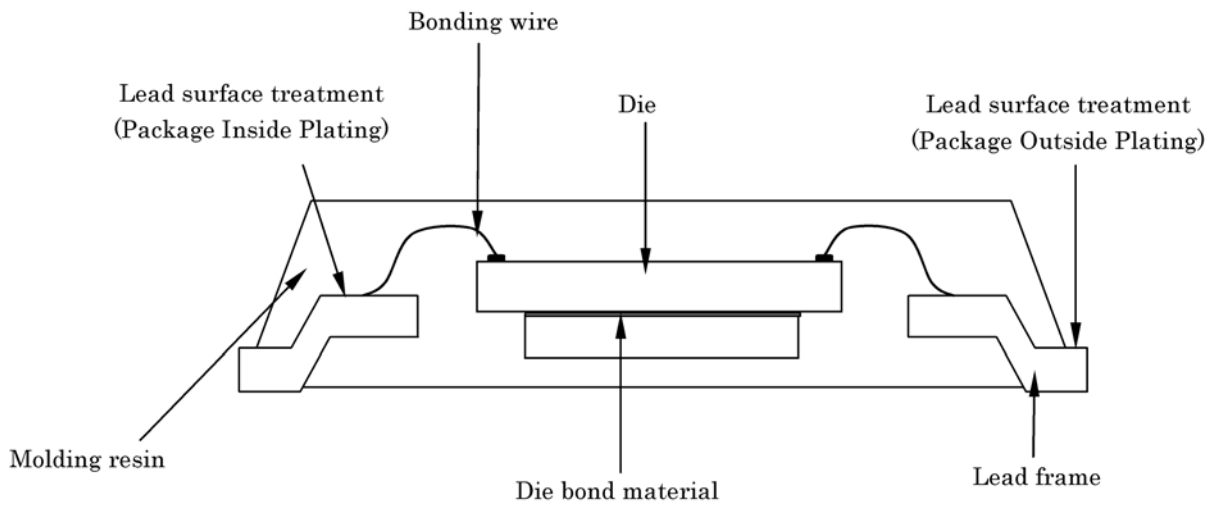
TS0N6-L1



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

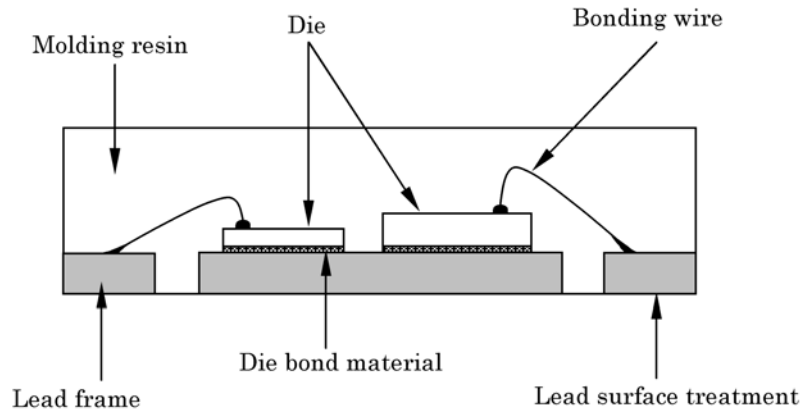
QFN20-M1/QFN28-N1/QFN48-Q1/QFN64-S4



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class of molding resin	: UL94V-0

INNER STRUCTURE

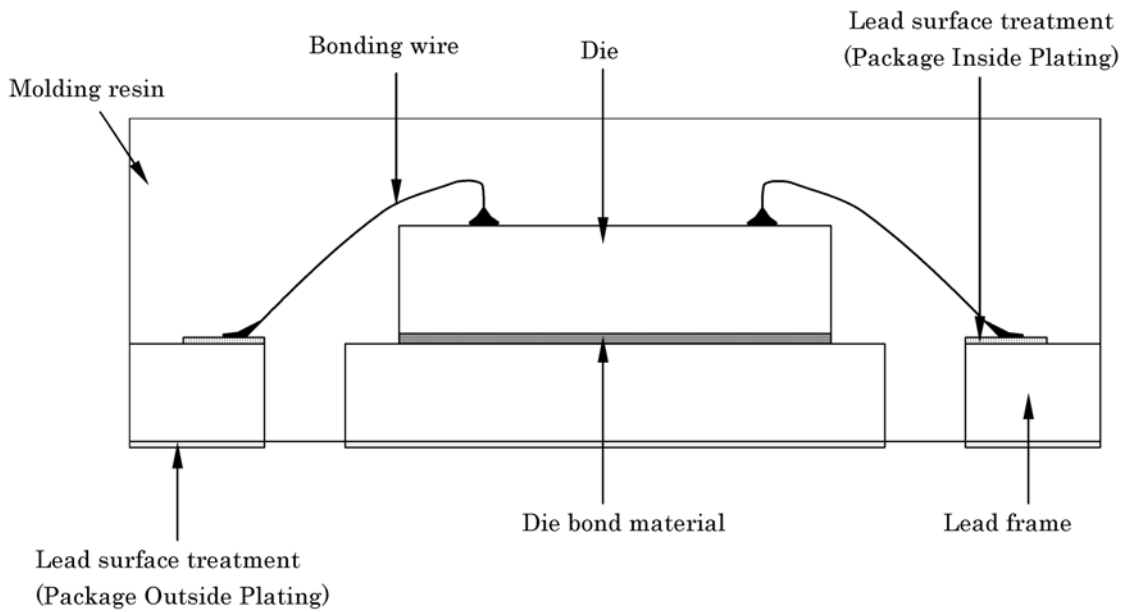
QFN24-T2



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class of molding resin	: UL94 V-0

INNER STRUCTURE

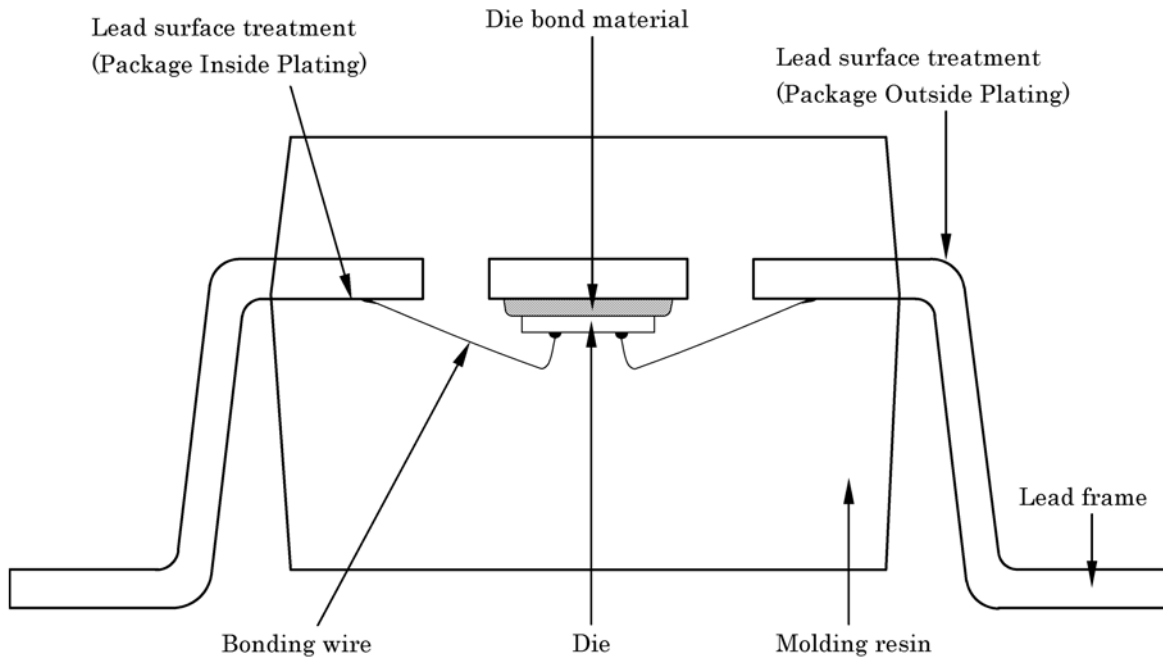
QFN12-11/QFN16-44/QFN24-34



Die Attach : Resin bonding method
Wire bonding method : Thermal-Sonic Bonding (TSB)
Mold method : Transfer mold
Flame class : UL94V-0

INNER STRUCTURE

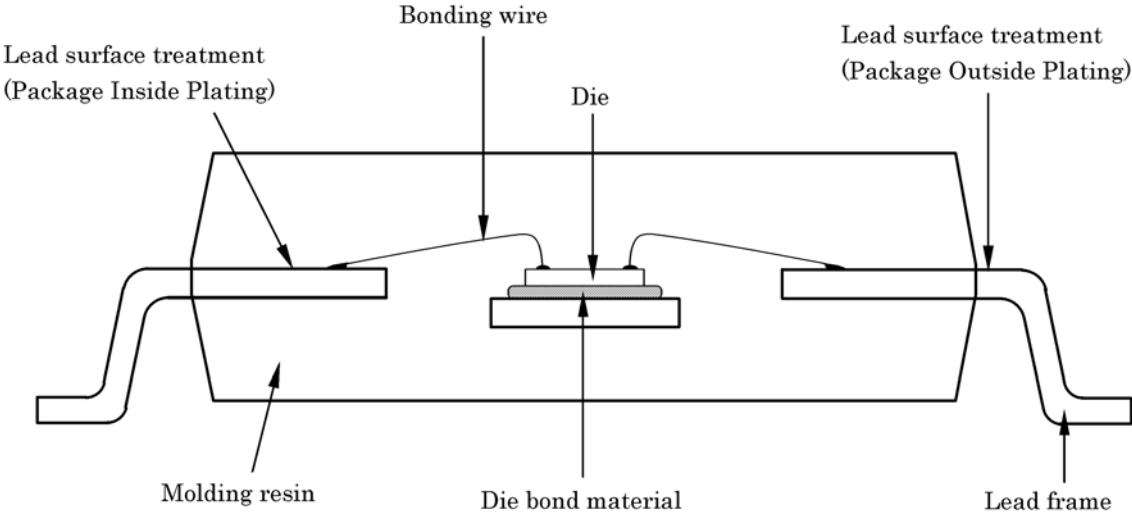
SC-88A/SC-82A/SOT-23



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

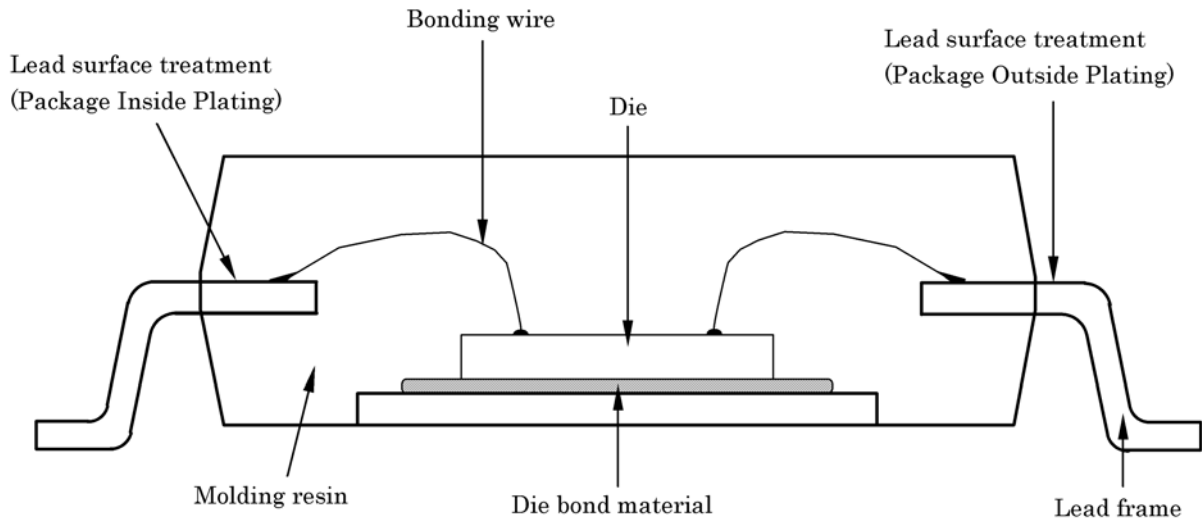
MSOP(VSP/TVSP)/SSOP/DMP/SOP/QFP



- Die Attach : Resin bonding method
- Wire bonding method : Thermal-Sonic Bonding (TSB)
- Mold method : Transfer mold
- Flame class : UL94V-0

INNER STRUCTURE

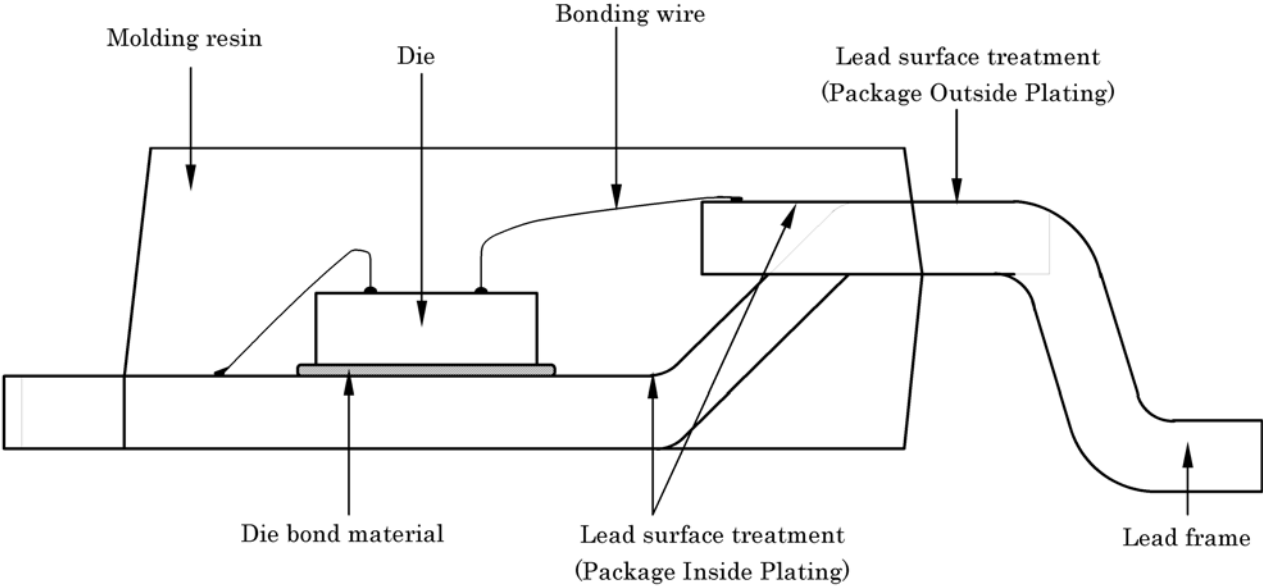
HSOP



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

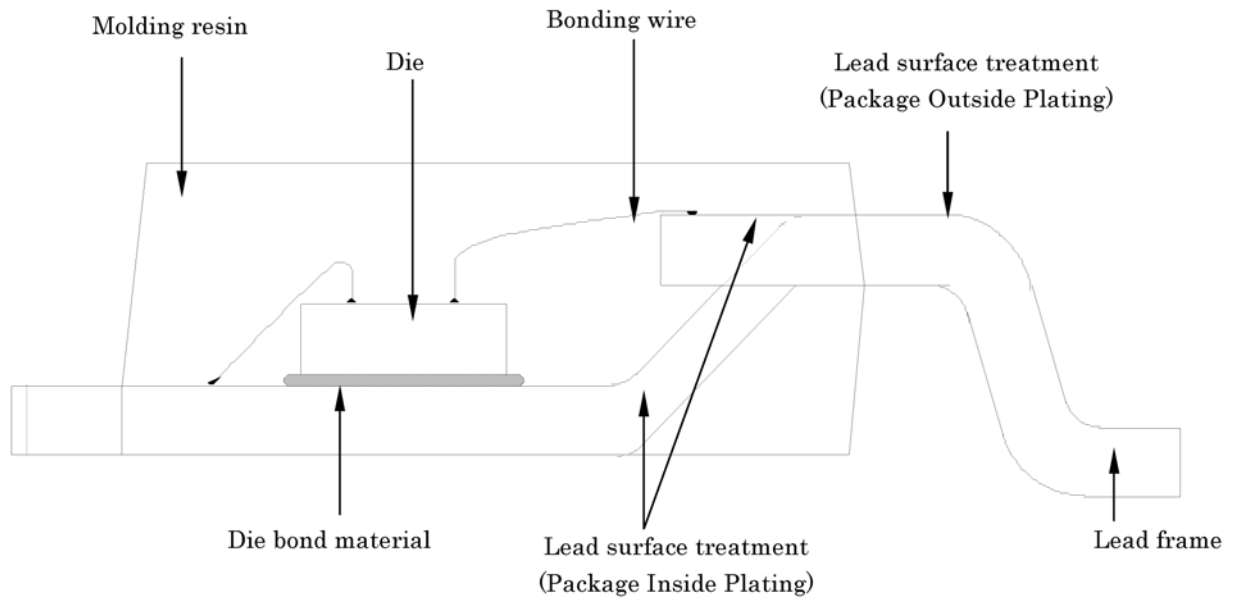
TO-252-3



- Die Attach : Resin bonding method
- Wire bonding method : Thermal-Sonic Bonding (TSB)
- Mold method : Transfer mold
- Flame class : UL94V-0

INNER STRUCTURE

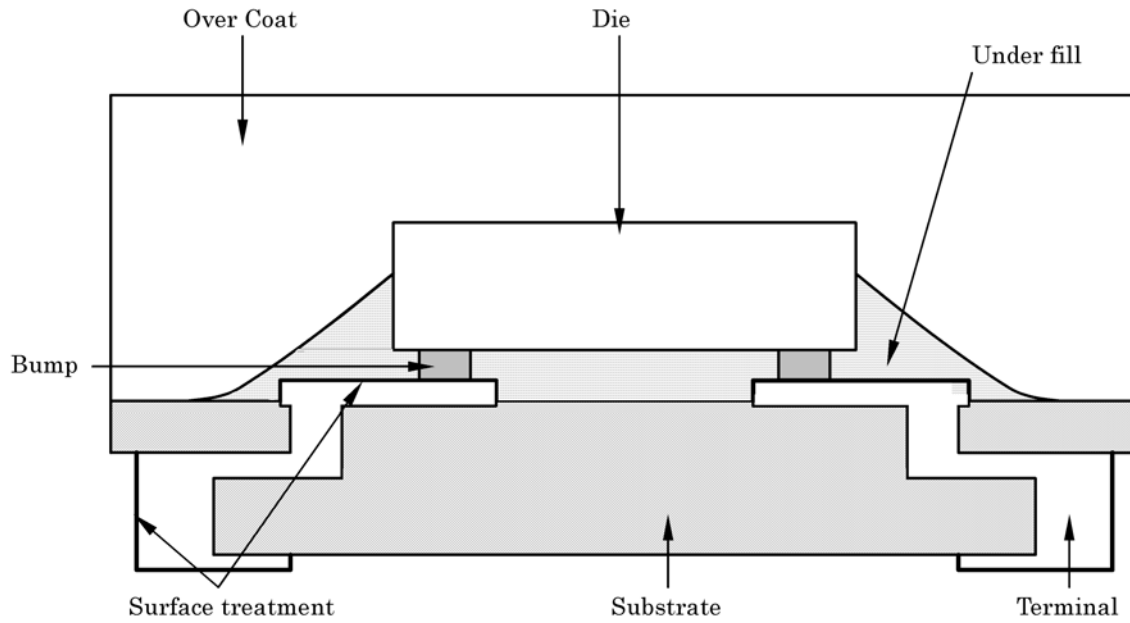
TO-252-5



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

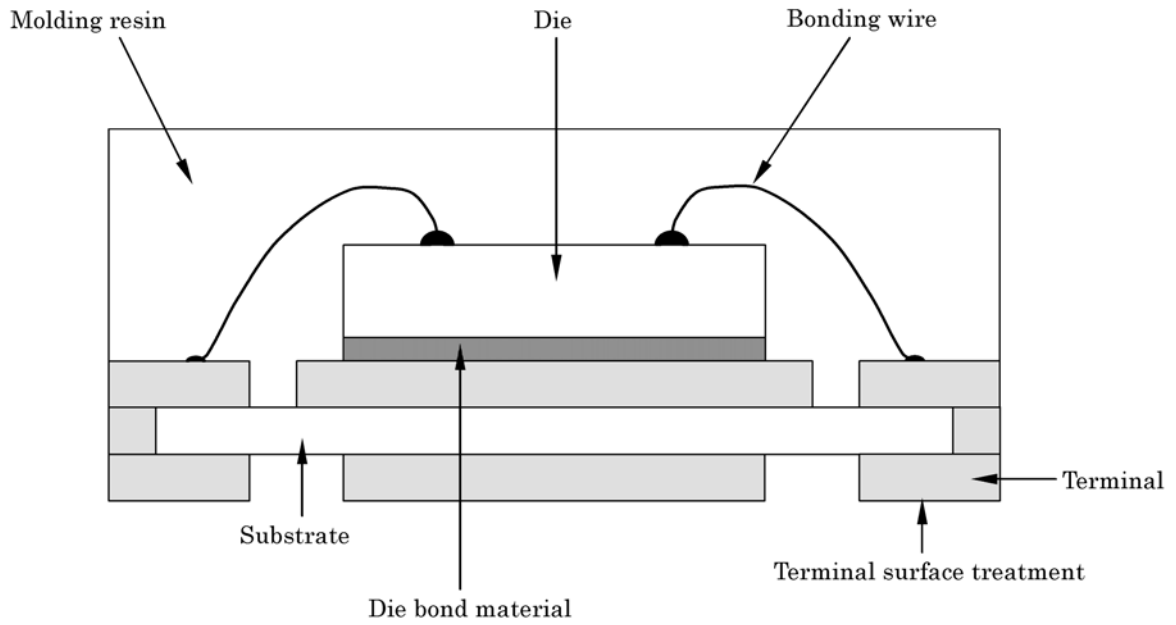
FFP8-S3/FFP16-B5/FFP12-B1/FFP12-B4/FFP16-C1/FFP24-E1



Bonding method : Thermal-Sonic Bonding (Flip chip bonding)
Mold method : Potting
Flame class : UL94V-0

INNER STRUCTURE

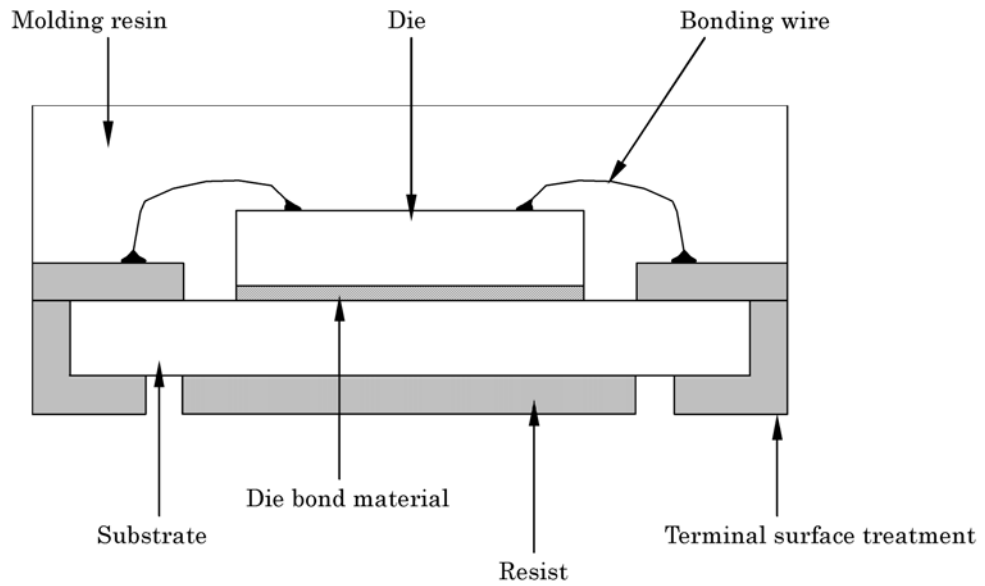
USB8-B3/USB8-B6/USB12-E3



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

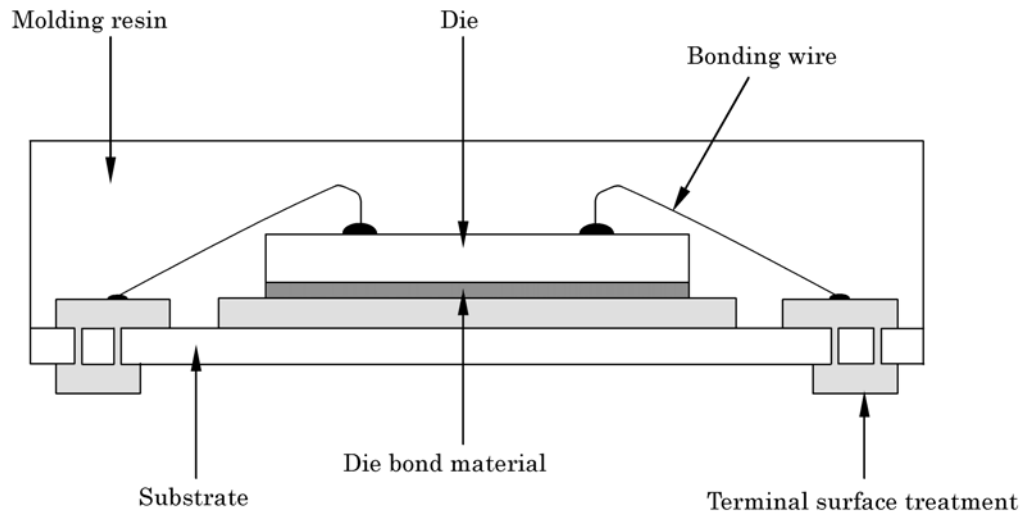
USB6-A8



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

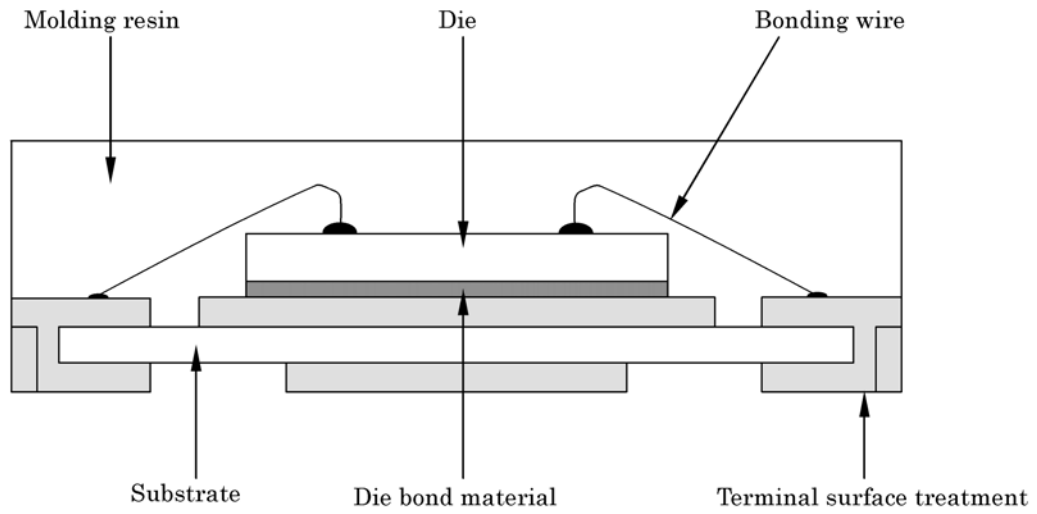
PSCP16-E4



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

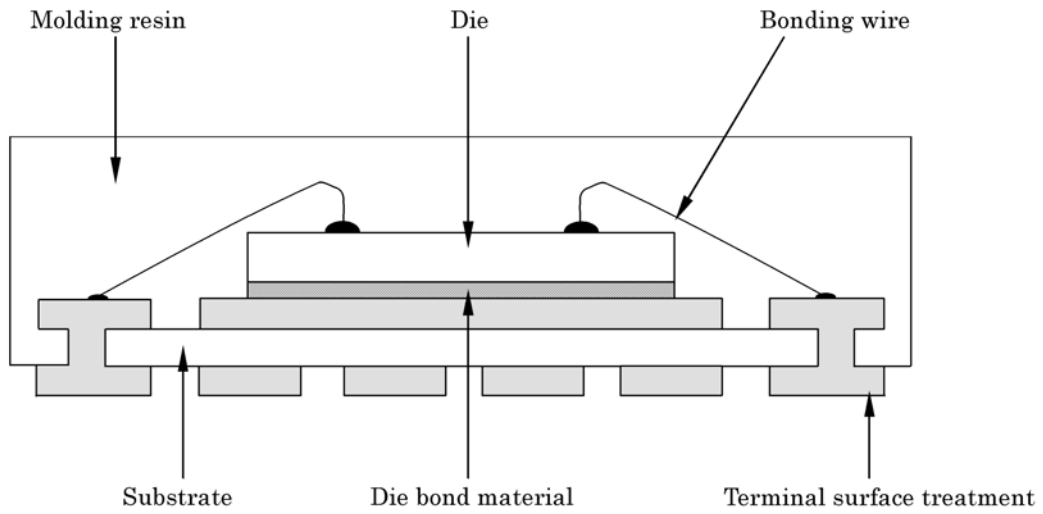
PCSP20-CC/PCSP14-C3/PCSP32-G3



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

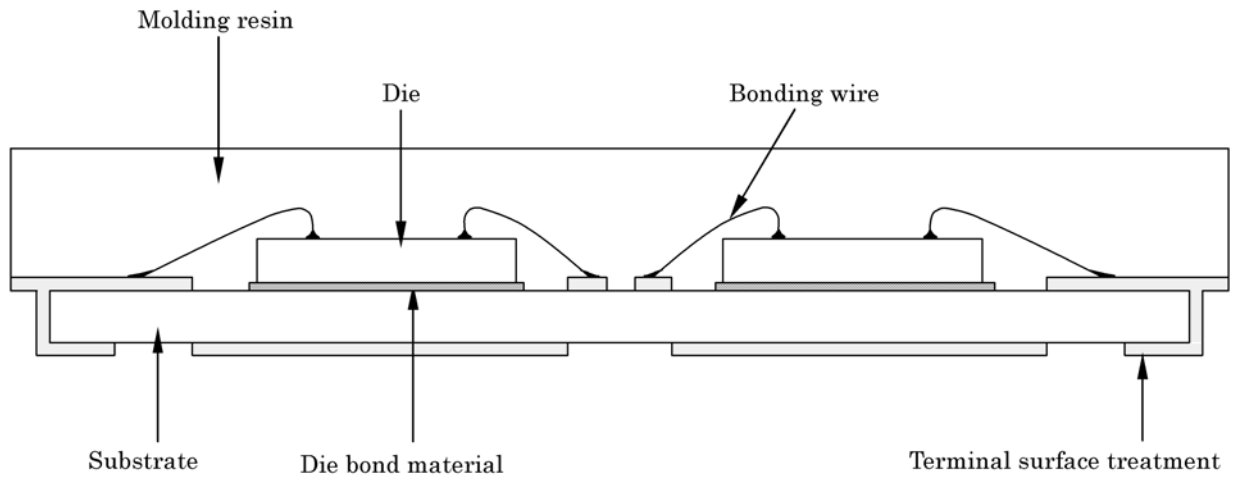
PCSP32-F7



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

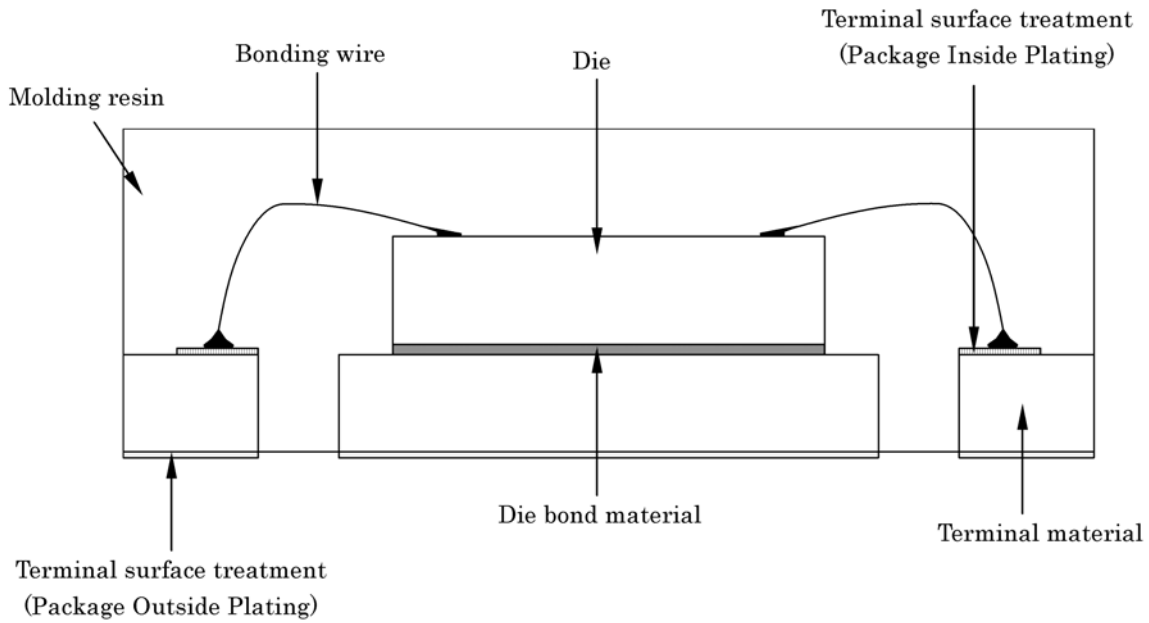
PCSP32-GD



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

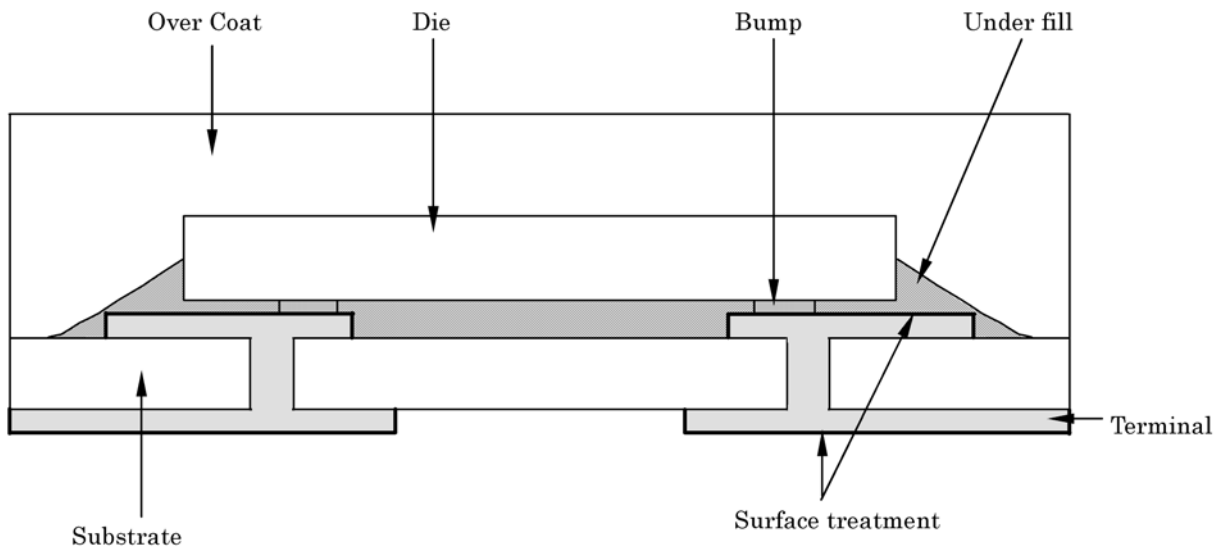
DFN4-F1(ESON4-F1)/DFN6-G1(ESON6-G1)/DFN8-U1(ESON8-U1)/ESON8-V1(DFN8-V1)/DFN8-W2(ESON8-W2)
EQFN12-E2/EQFN14-D7/EQFN18-E7/EQFN16-G2/EQFN12-JE/EQFN16-JE



Die Attach	: Resin bonding method
Wire bonding method	: Thermal·Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0

INNER STRUCTURE

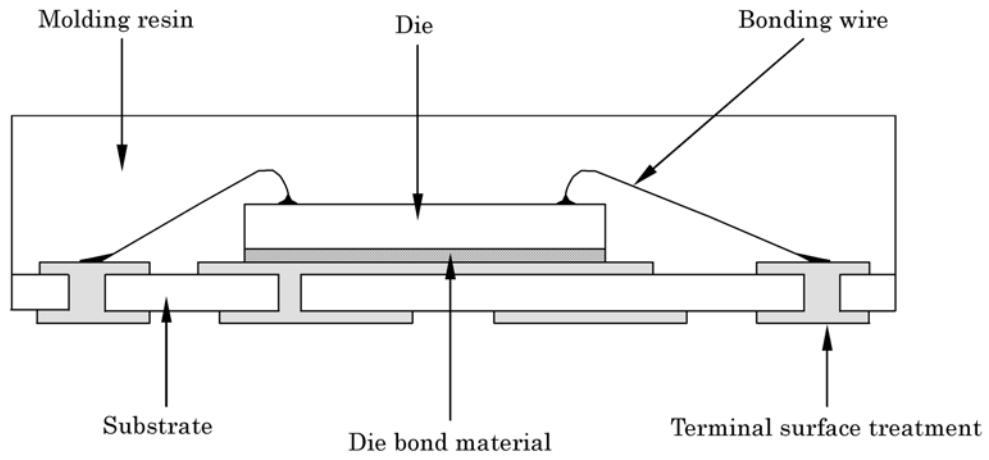
EPFFP6-A2



Bonding method : Thermal-Sonic Bonding (Flip chip bonding)
Mold method : Transfer mold
Flame class : UL94 V-0

INNER STRUCTURE

LCSP20-H4



Die Attach	: Resin bonding method
Wire bonding method	: Thermal-Sonic Bonding (TSB)
Mold method	: Transfer mold
Flame class	: UL94V-0